

IN THE SPECIFICATION

Please amend the paragraph beginning at page 3, line 5 as follows:

Figure 1 shows an electronic assembly 100 that includes an integrated circuit (e.g., processor 120) that is mounted on a substrate (e.g., motherboard 123). The electronic assembly further includes a radial heat sink 200 that is thermally coupled to the processor 120. Radial heat sink 200 includes a thermally conductive core 210 having an outer surface 212 and a plurality of non-planar helical fins 219 that extend from the outer surface 212 of core 210. The interface between processor 120 and radial heat sink 200 may further include other components, including but not limited to, thermal interfaces (e.g., thermal grease and phase-change materials) and integrated heat spreaders.